FIG. 1A

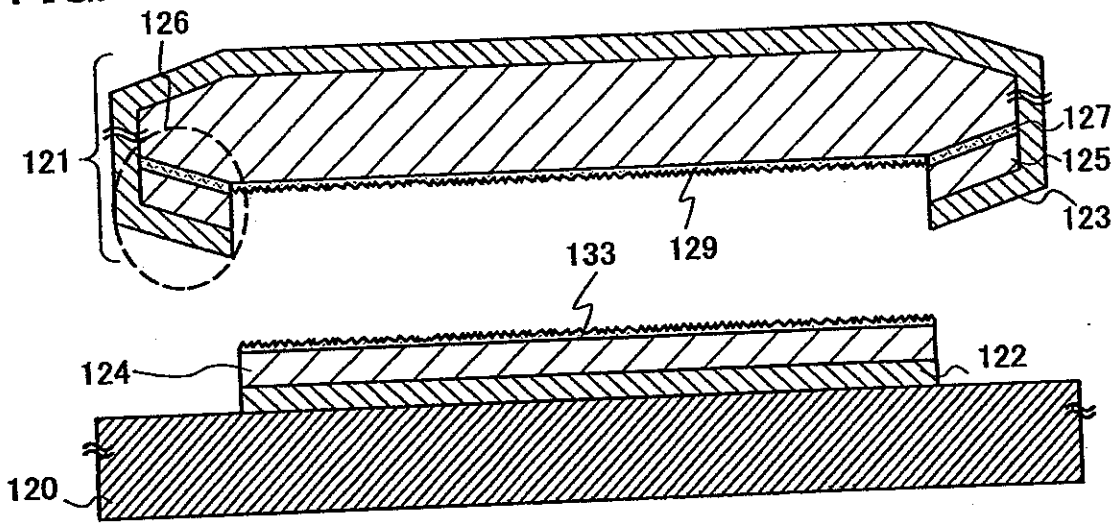


FIG. 1B

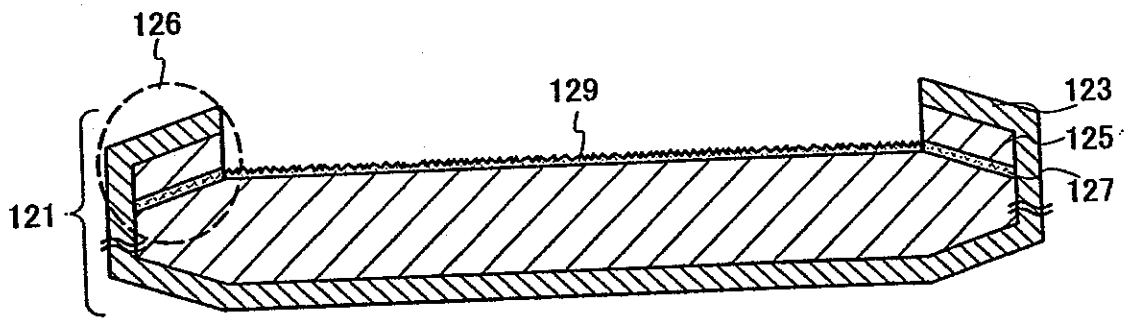


FIG. 1C

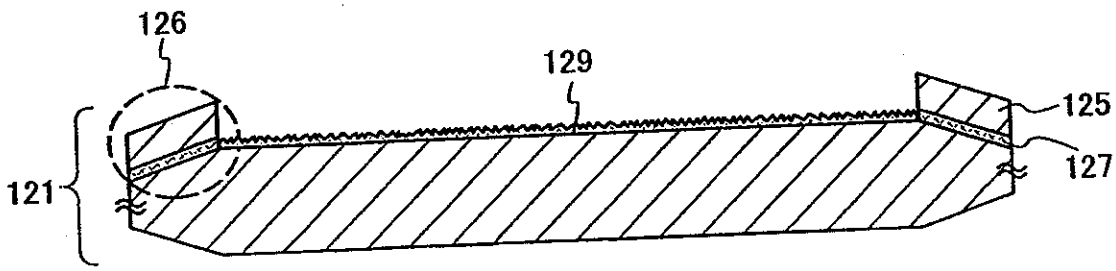


FIG. 1D

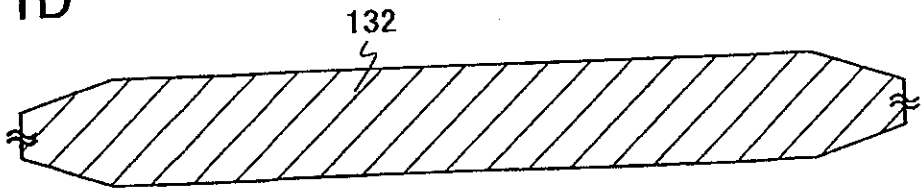


FIG. 2A

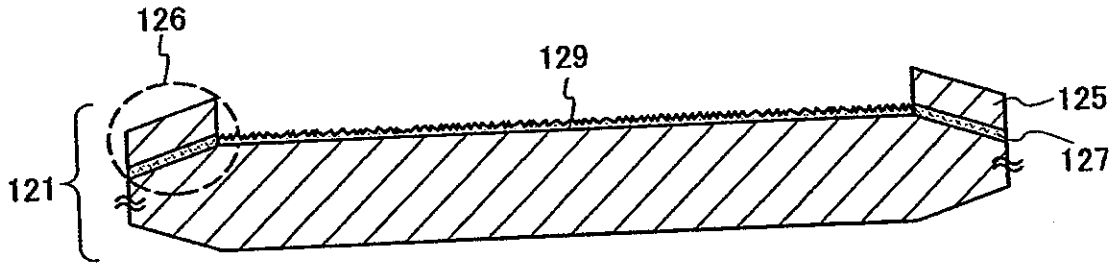


FIG. 2B

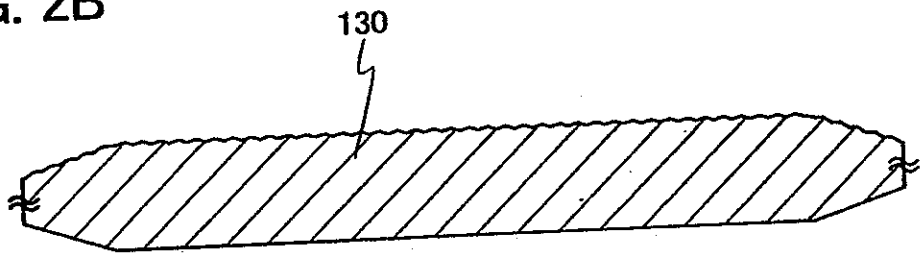


FIG. 2C

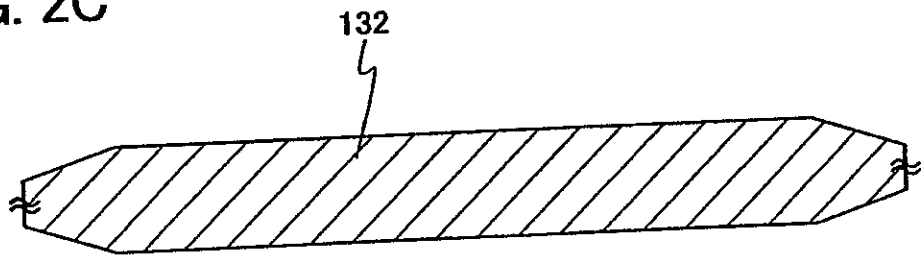


FIG. 3A

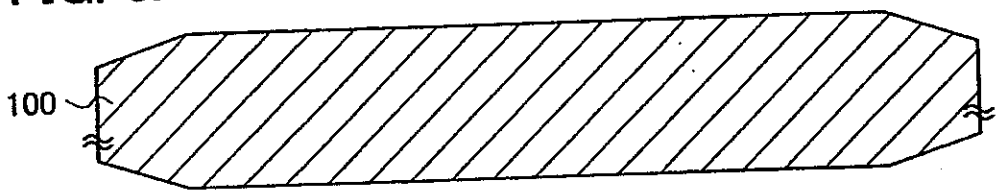


FIG. 3B

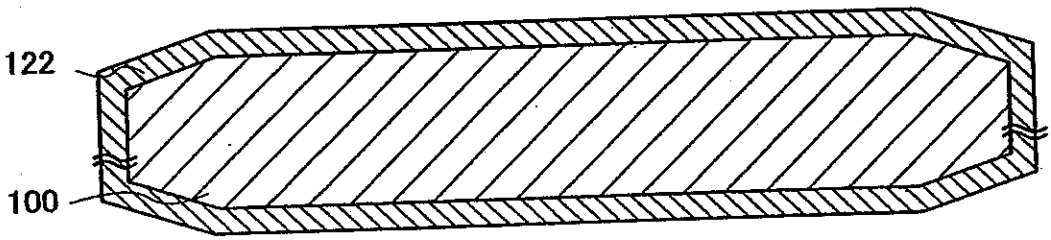


FIG. 3C

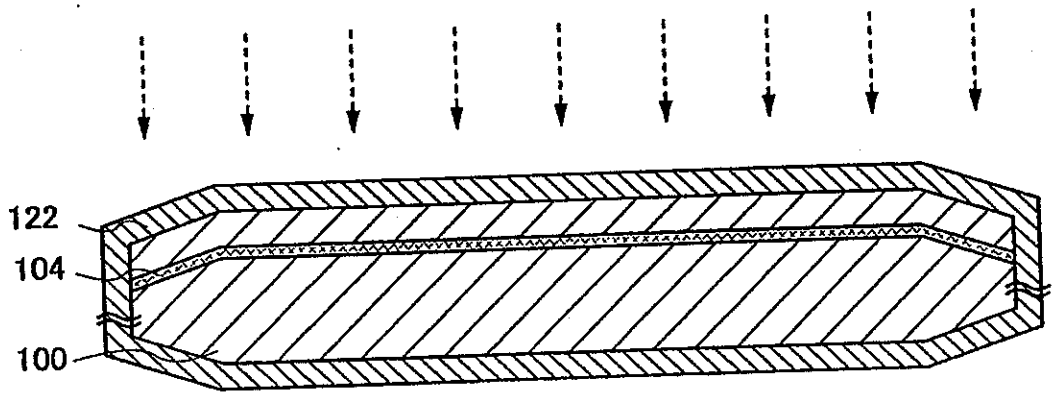


FIG. 4A

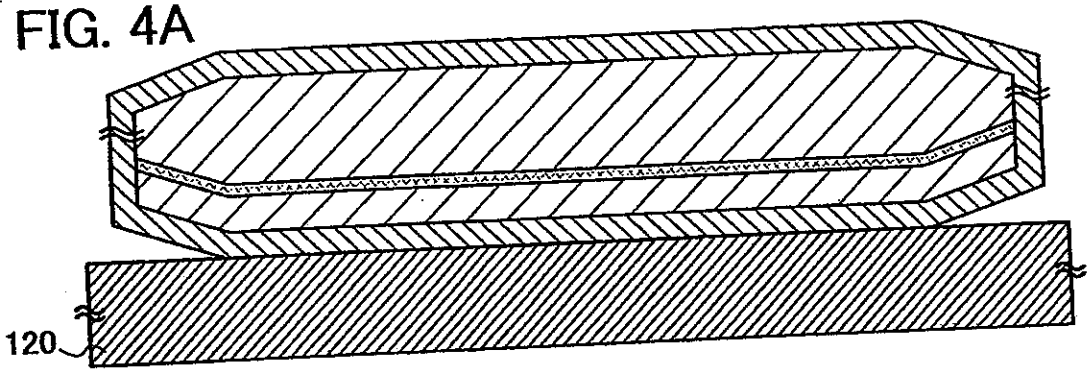


FIG. 4B

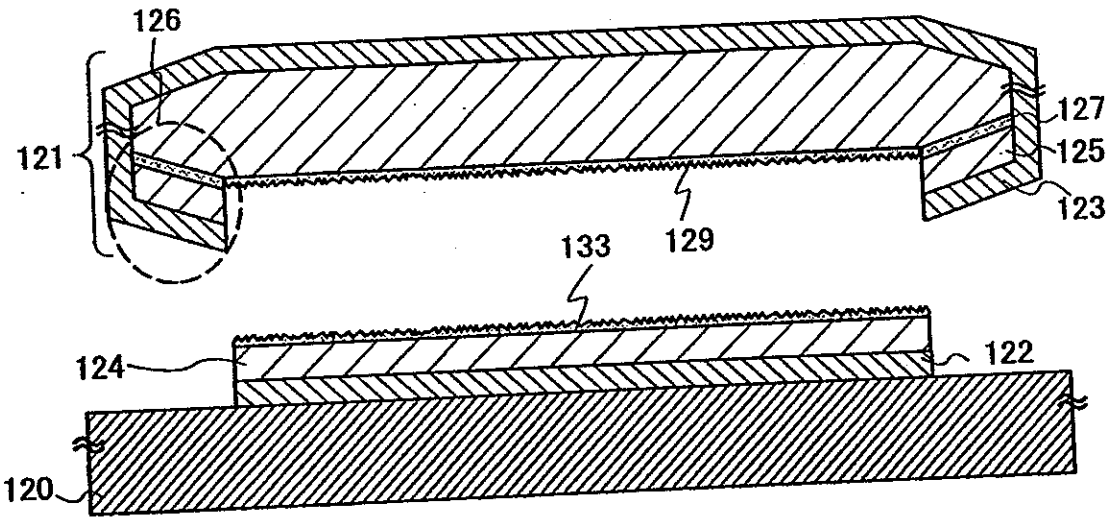


FIG. 4C

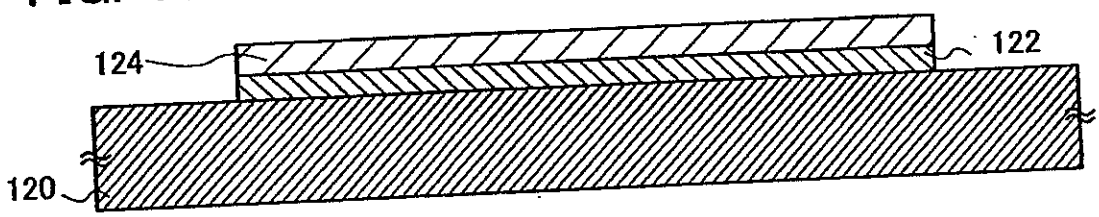


FIG. 5A

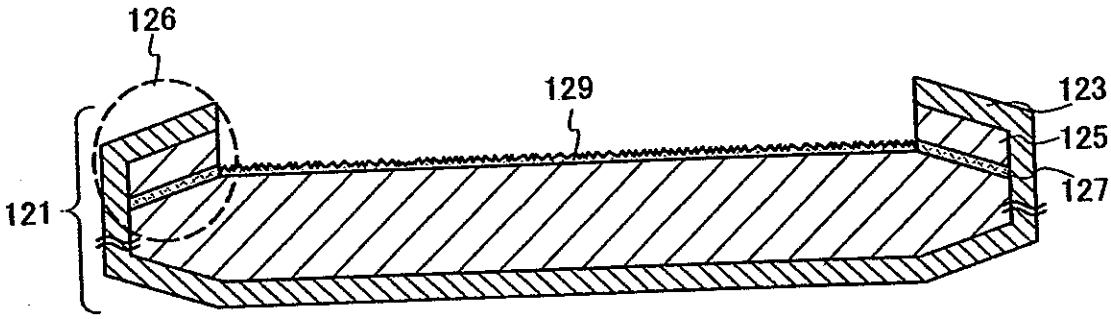


FIG. 5B

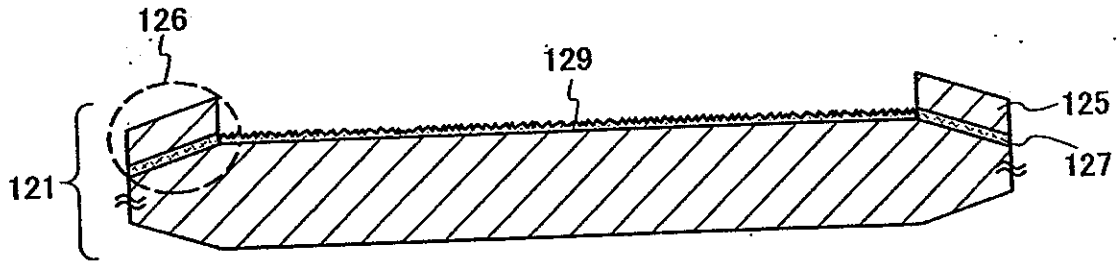


FIG. 5C

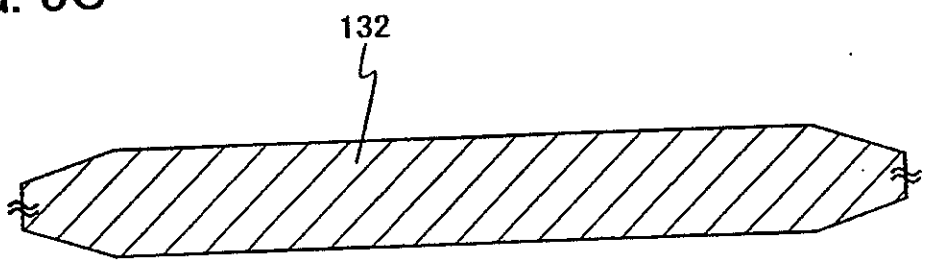


FIG. 6

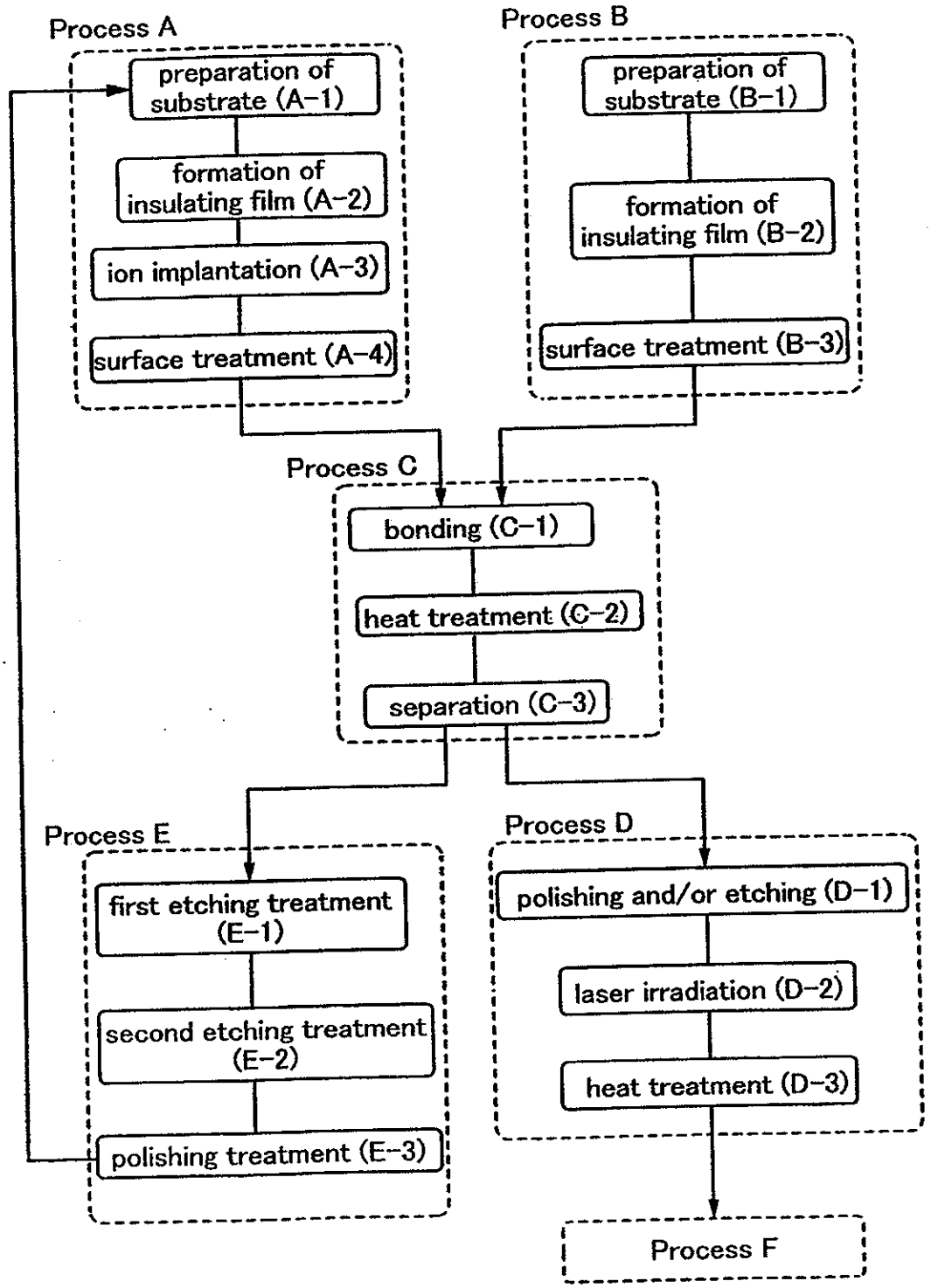
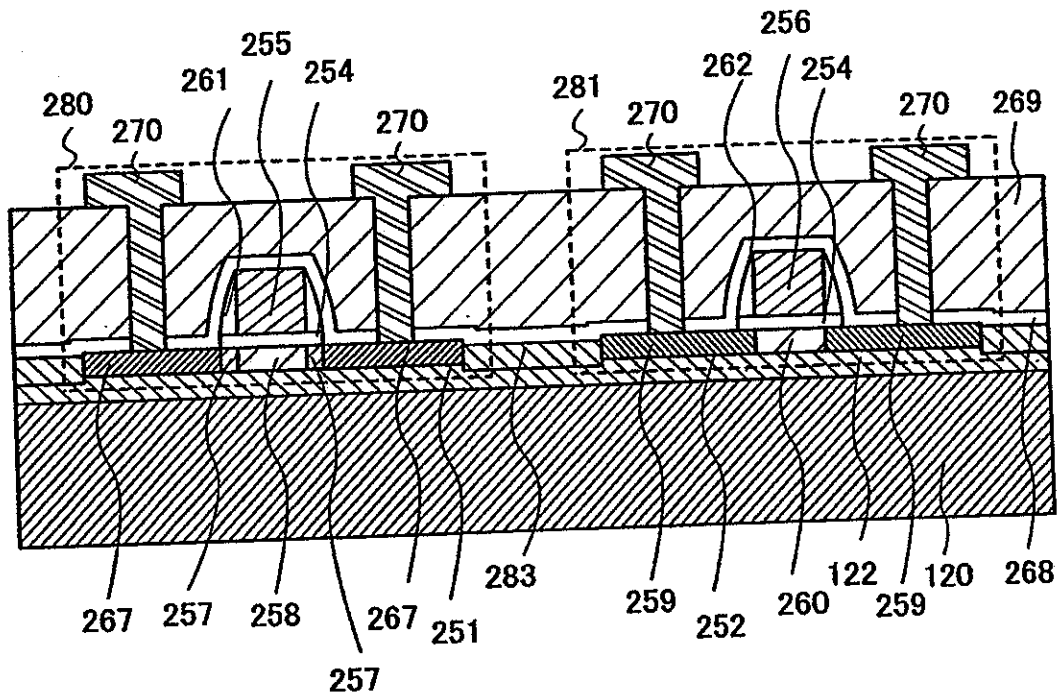

Process A
preparation of substrate (A-1)
formation of insulating film (A-2)
ion implantation (A-3)
surface treatment (A-4)
Process B
preparation of substrate (B-1)
formation of insulating film (B-2)
surface treatment (B-3)
Process C
bonding (C-1)
heat treatment (C-2)
separation (C-3)
Process E
first etching treatment (E-1)
second etching treatment (E-2)
polishing treatment (E-3)
Process D
polishing and/or etching (D-1)
laser irradiation (D-2)
heat treatment (D-3)
Process F

FIG. 7


280
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